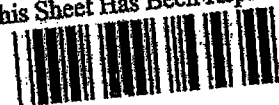


ABSTRACT OF THE DISCLOSURE

There are provided a circuit-forming substrate comprising a long stainless steel foil having formed on one surface or both surfaces thereof a polyimide resin layer wholly or partially, and a circuit substrate formed by using the circuit-forming substrate, wherein a conductor layer is finely patterned on the circuit-forming substrate. The circuit-forming substrate sufficiently satisfies low cost, high density and high reliability, scarcely causes warping of the substrate itself, and has excellent workability.

This Sheet Has Been Replaced



THIS SHEET HAS BEEN
REPLACED